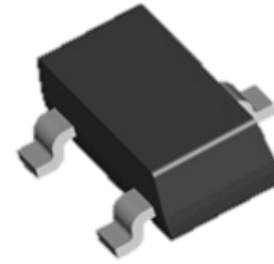


Applications

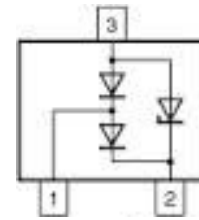
- Personal Digital Assistance
- Wireless System
- DVI
- High Speed Data Line
- Ethernet
- USB interfaces(2.0)



SOT23

Feature

- Max working voltage:5V
- ESD Protection:Level 4
- Low clamping voltage
- Protection one Hi-speed Data Line.
- Ultra low capacitance:1.5pf max.(any I/O to GND.)



IEC Compatibility

- EN61000-4
- 61000-4-2(ESD):
Level 4,Contact:±8kv,Air:±15kv
- 61000-4-4(EFT):40A-5/50ns
- 61000-4-5(Surge):5A,8/20us

Mechanical Characteristics

- Molded JEDEC SOT23 package
- Packaging:Tape and Reel
- Flammability rating UL 94V-0
- Halgen Free

Device Characteristics

Maximum Ratings@25 unless otherwise specified			
Parameter	Symbol	Value	Units
Reverse standoff voltage	V_{RWM}	5.5	V
Operating Temperature	T_J	-55~150	°C
Storage Temperature	T_{STG}	-55~150	°C

Electrical Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Reverse Stand-off Voltage	V_{RWM}				5.5	V
Reverse Breakdown Voltage	V_{BR}	$I_z=1mA$ Pin2 to 3	6.0		9.0	V
Reverse Leakage Current	$I_{R@V_R=3V}$	Pins 1 to 3.			100	nA
Forward Voltage	V_F	$I_F=10mA$		0.7		V
Junction Capacitance	$C_{I/O}$	Pin capacitance to GND. $V_{dc}=0V, f=1MHz$		1	1.5	pf

Rating and characteristic curve

Figure 1 I/O port to GND capacitance

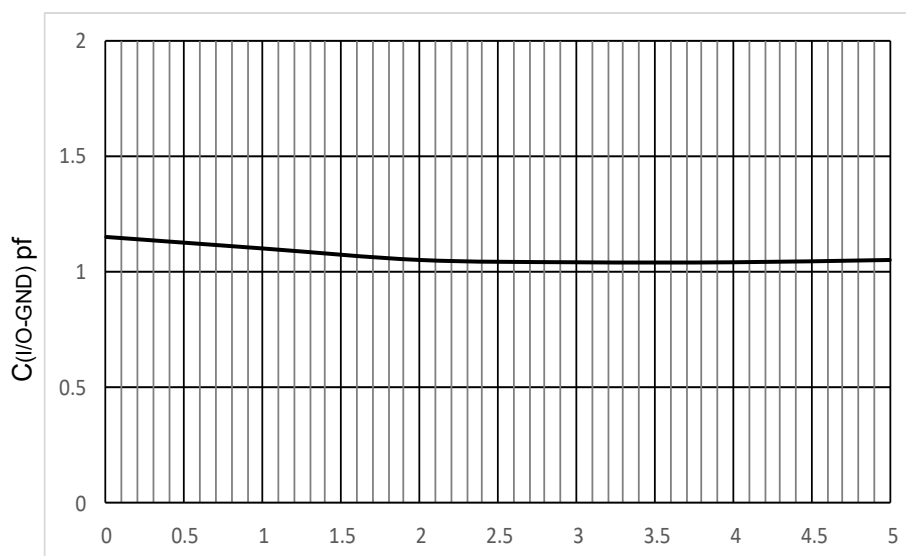

 $V_R(V) f=1MHz, T=25^\circ C$

Figure 2
Power Derating Curve

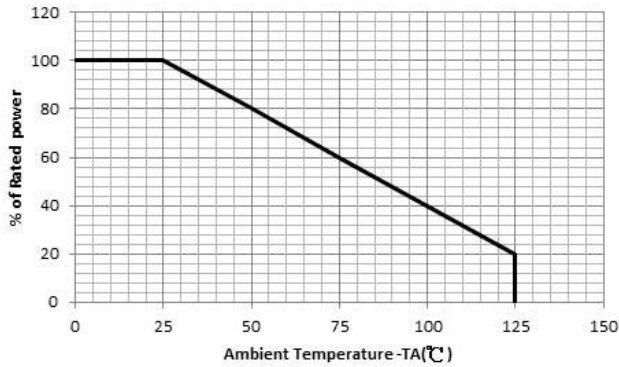
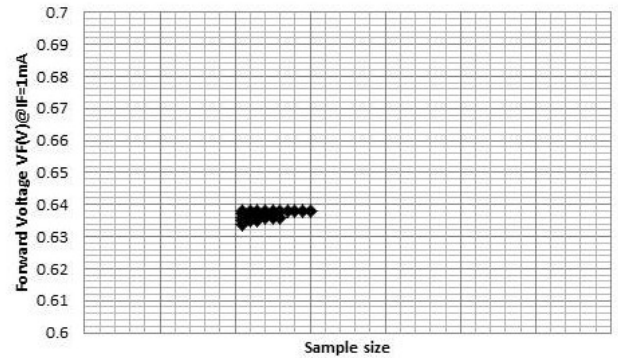
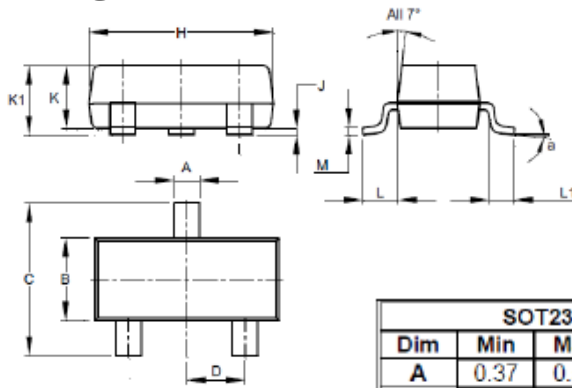


Figure 3
Forward Voltage VF Map

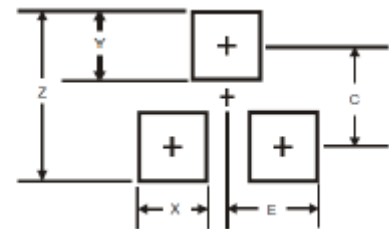
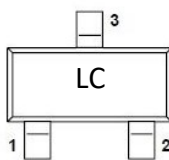


Package Information



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.890	1.00	0.975
K1	0.903	1.10	1.025
L	0.45	0.61	0.55
L1	0.25	0.55	0.40
M	0.085	0.150	0.110
a	8°		
All Dimensions in mm			

Marking Code



Dimensions	SOT23
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35



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